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Patent
Docket No.: 53434USA8C.009

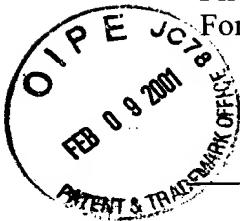
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Peter B. Hogerton, Kevin Yu Chen, Joel
A. Gerber and Robert L. D. Zenner

Serial No.: 09/690,600
Filed: October 17, 2000
For: SOLVENT ASSISTED
BURNISHING OF PRE-
UNDERFILLED SOLDER-
BUMPED WAFERS FOR
FLIPCHIP BONDING

Group Art Unit: 3729

Examiner:



REQUEST FOR EXTENSION OF TIME UNDER 37 C.F.R. 1.136(a)

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicants respectfully petition the Commissioner for Patents to extend the time for response to the Notice to File Missing Parts of Nonprovisional Application dated November 27, 2000 for one (1) month from January 27, 2001 to February 27, 2001.

Please charge the fee provided in 37 C.F.R. 1.17(a) to Deposit Account No. 13-3723. Please also charge any additional fees or credit any overpayment to Deposit Account No. 13-3723. One copy of this sheet marked DUPLICATE is also enclosed.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Matthew B. McNutt".

Matthew B. McNutt
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Please charge any additional fees or credit any over payment to Deposit Account No. 13-3723. I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on: 2-6-01

Signed:
Tom Sanders